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APPROVED BY: DATE:	ELECTRONIC COMPONE GROUP SHARP CORPOR	· I	REPRESEN	TATIVE DIVISION
J. Yoshikana Sap 30 1997	SPECIFICATION	NAT	OPTO-ELEC	TRONIC DEVICES DIV
	PHOTOCOUPLER	PC3H	4	
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1. Application

This specification applies to the outline and characteristics of photocoupler; Model No. PC3H4.

2. Outline

Refer to the attached drawing No. CY8374K02.

3. Ratings and characteristics

Refer to the attached sheet, page 4 to 6.

4. Reliability

Refer to the attached sheet, page 7.

5. Incoming inspection

Refer to the attached sheet, page 8.

6. Supplement

- 6.1 Isolation voltage shall be measured in the following method.
 - (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
 - (2) The dielectric withstand tester with zero-cross circuit shall be used.
 - (3) The wave form of applied voltage shall be a sine wave.

6.2 Packaging specifications

Refer to the attached sheet, page 9 to 11.

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6.3 Collector current (Ic) Delivery rank table

("O" mark: indicates business dealing name of ordered product)

Ordered product	Business dealing name	Rank mark	Ic (mA)	Test conditions
	РСЗН4	A or no mark	0.2 to 4.0	I _F =±1mA
	РСЗН4А	A	0.5 to 1.5	V _{CE} =5V, Ta=25℃

High temperature test are carried out at production process.

6.4 This Model is approved by UL.

Approved Model No.: PC3H4

UL file No.: E64380

- 6.5 This product is AC input type.
- 6.6 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

6.7 ODS materials

This product shall not contain the following materials. Also, the following materials shall not be used in the production process for this product.

Materials for ODS: CFC_S, Halon, Carbon tetrachloride,

 $1.1.1 - Trichloroethane \, (Methylchloroform)$

6.8 Brominated flame retardants

Specific brominated flame retardants such as the $PBBO_S$ and PBB_S are not used in this device at all.

7. Notes

Refer to the attached sheet-1-1, 2.

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Anode mark

Pate code *1

Rank mark

S

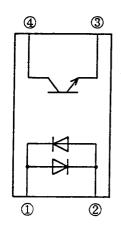
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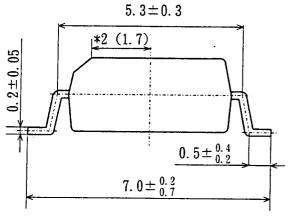
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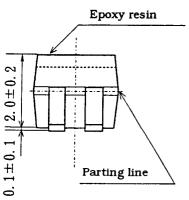
Anode mark

Burr Max. 0.2

Pin Nos. and internal connection diagram







- *1) 2-digit number shall be marked according to DIN standard.
- *2) Dimensions in parenthesis are shown for reference.

Product mass: Approx. 0.05g

UNIT: 1/1 mm			
Name	PC3H4 Outline Dimensions (Business dealing name : PC3H4)		
Drawing No.	CY8374K02		

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3. Ratings and characteristics

3.1 Absolute maximum ratings

Ta=25℃

	Parameter	Symbol	Rating	Unit
	*1 Forward current	$I_{\mathbf{F}}$	±50	mA
Input	*2 Peak forward current	I_{FM}	±1	A
	*1 Power dissipation	P	70	mW
	Collector-emitter voltage	V_{CEO}	70	v
Outmut	Emitter-collector voltage	V _{ECO}	6	V
Output	Collector current	Ic	50	mA
	*1 Collector power dissipation	Pc	150	mW
*1 Total power dissipation		Ptot	170	mW
Operating temperature		Topr	-30 to +100	C
Storage temperature		Tstg	-40 to +125	C
*3 Isolation voltage		Viso	2.5	kVrms
*4 Soldering temperature		Tsol	260	Ĉ

^{*1} The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1 to 4.

^{*2} Pulse width $\leq 100 \,\mu$ s, Duty ratio : 0.001 (Refer to Fig. 5)

^{*3} AC for 1 min, 40 to 60%RH, f=60Hz

^{*4} For 10 s

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3.2 Electro-optical characteristics

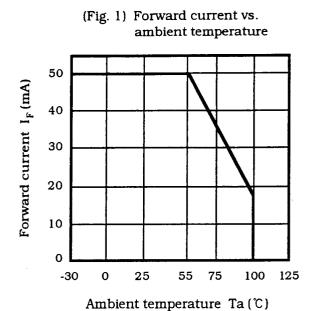
Ta=25℃

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Forward voltage	V _F	I _F =±20mA	-	1.2	1.4	V
Input	Terminal capacitance	Ct	V=0, f=1kHz	•	30	250	pF
	Dark current	I _{CEO}	V_{CE} =50V, I_F =0	-	•	100	nA
Output	Collector-emitter breakdown voltage	BV _{CEO}	Ic=0.1mA I _F =0	70	•	-	V
	Emitter-collector breakdown voltage	BV _{ECO}	$I_{\rm E}$ =10 μ A, $I_{\rm F}$ =0	6	-	•	v
	Collector current	Ic	$I_F = \pm 1 \text{mA}, V_{CE} = 5V$	0.2	•	4.0	mA
	Collector-emitter saturation voltage	V _{CE(sat)}	I _F =±20mA Ic=1mA	-	0.1	0.2	V
Transfer charac-	Isolation resistance	Riso	DC500V 40 to 60%RH	5×10 ¹⁰	1011	-	Ω
teristics	Floating capacitance	Cſ	V=0, f=1MHz	-	0.6	1.0	pF
	Response time (Rise)	tr	V _{CE} =2V Ic=2mA	-	4	18	μs
	Response time (Fall)	tf	$R_L=100 \Omega$	-	3	18	μs

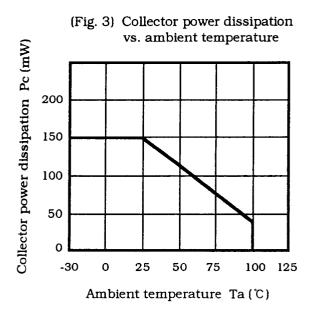
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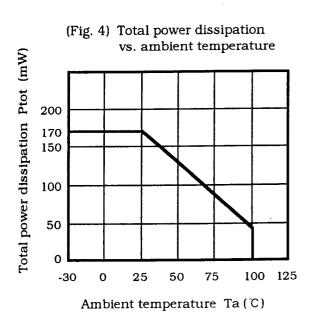
vs. ambient temperature

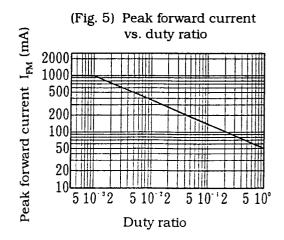
(Fig. 2) Diode power dissipation



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Pulse width ≦100 μs Ta=25℃

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Confidence level: 90%

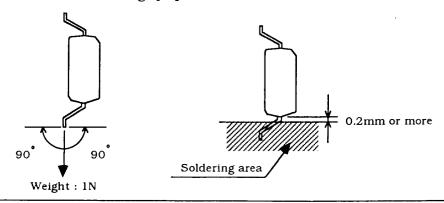
LTPD: 10%/20%

4. Reliability

The reliability of products shall satisfy items listed below.

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n) Defective(C)
Solderability *2	230°C, 5 s		n=11, C=0
Soldering heat *3	260°C, 10 s		n=11, C=0
Terminal strength (Bending) *4	Weight: 1N 1 time/each terminal	V _F >U×1.2	n=11, C=0
Mechanical shock	15000m/s^2 , 0.5 ms 3 times/ $\pm X$, $\pm Y$, $\pm Z$ direction	$I_{CEO} > U \times 2$ $I_{C} < L \times 0.7$	n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/4min 200m/s ² 4 times/ X, Y, Z direction	$V_{\text{CE(sat)}} > U \times 1.2$	n=11, C=0
Temperature cycling	1 cycle -40°C to +125°C (30min) (30min) 20 cycles test	II II	n=22,C=0
High temp. and high humidity storage	+85°C, 85%RH, 500h *5	U : Upper specification limit	n=22,C=0
High temp. storage	+125°C, 1000h	L: Lower	n=22,C=0
Low temp. storage	-40°C, 1000h	specification limit	n=22,C=0
Operation life	I _F =±50mA, Ptot=170mW Ta=25℃, 1000h		n=22,C=0

- *1 Test method, conforms to JIS C 7021.
- *2 Solder shall adhere at the area of 95% or more of immersed portion of lead, and pin hole or other holes shall not be concentrated on one portion.
- $*3\,$ The lead pin depth dipped into solder shall be 0.2mm away from the root of lead pins.
- *4 Terminal bending direction is shown below.
- *5 It evaluates after washing by specified solvent in attach sheet-1-1.



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- 5. Incoming inspection
 - 5.1 Inspection items
 - (1) Electrical characteristics

$$V_{F}$$
, I_{CEO} , $V_{CE(sat)}$, Ic, Riso, Viso

- (2) Appearance
- 5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.1
Minor defect	Appearance defect except the above mentioned.	0.4

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6.2 Package specifications

6.2.1 Taping conditions

(1) Tape structure and Dimensions (Refer to the attached sheet, Page 10)

The tape shall have a structure in which a cover tape is sealed heat-pressed on the carrier tape of protect against static electricity.

(2) Reel structure and Dimensions (Refer to the attached sheet, Page 11)

The taping reel shall be of plastic with its dimensions as shown in the attached drawing.

(3) Direction of product insertion (Refer to the attached sheet, Page 11)

Product direction in carrier tape shall direct to the anode mark at the hole side on the tape.

(4) Joint of tape

The cover tape and carrier tape in one reel shall be jointless.

(5) The way to repair taped failure devices

The way to repair taped failure devices cut a bottom of carrier tape with a cutter, and after replacing to good devices, the cut portion shall be sealed with adhesive tape.

6.2.2 Adhesiveness of cover tape

• The exfoliation force between carrier tape and cover tape shall be 0.2N to 0.7N for the angle from 160° to 180°.

6.2.3 Rolling method and quantity

• Wind the tape back on the reel so that the cover tape will be outside the tape. Attach more than 20cm of blank tape to the trailer and the leader of the tape and fix the both ends with adhesive tape. One reel shall contain 3000pcs.

6.2.4 Marking

- The outer packaging case shall be marked with following information.
- * Model No. * Number of pieces delivered * Production date

6.2.5 Storage condition

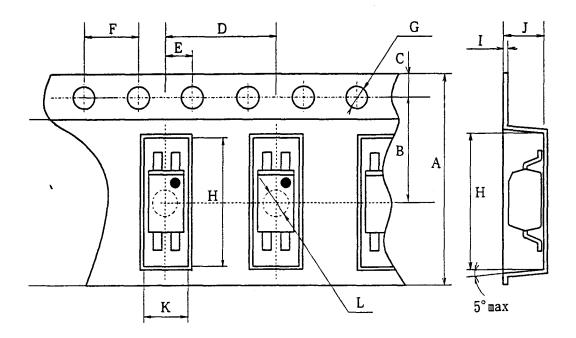
• Taped products shall be stored at the temperature 5 to 30°C and the humidities lower than 70%RH.

6.2.6 Safety protection during shipping

• There shall be no deformation of component or degradation of electrical characteristics due to shipping.

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Carrier tape structure and Dimensions

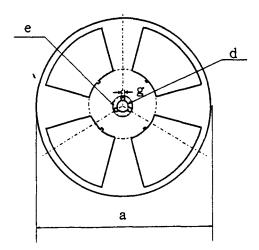


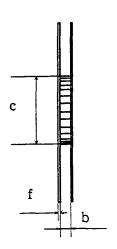
Symbol Unit	A	В	С	D	E	F
mm	±0.3	±0.1	±0.1	±0.1	±0.1	±0.1
	12.0	5.5	1.75	8.0	2.0	4.0

Symbol Unit	G	Н	I	J	K	L
mm	+0.1 -0.0 \$ 1.5	±0.1 7.5	±0.05 0.3	±0.1 2.3	±0.1 3.1	+0.1 -0.0 \$ 1.6

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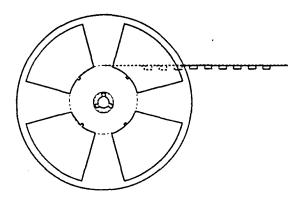
Reel structure and Dimensions



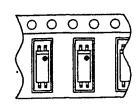


Symbol		Check word					
Unit	а	b	С	d	е	f	g
mm	330	13.5±1.5	100±1	13±0.5	23±1	2.0±0.5	2.0±0.5

Direction of product insertion



Pull-out direction



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sheet-1-1

Precautions for Photocouplers

1 For cleaning

(1) Solvent cleaning: Solvent temperature 45°C or less Immersion for 3 min or less

(2) Ultrasonic cleaning: The effect to device by ultrasonic cleaning differs

by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting

the ultrasonic cleaning.

(3) Applicable solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

In case when the other solvent is used, there are cases that the packaging resin is eroded. Please use the other solvent after thorough confirmation is performed in actual using condition.

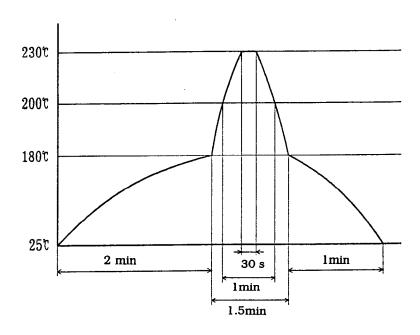
- 2. The LED used in the Photocoupler generally decreases the light emission power by operation. In case of long operation time, please design the circuit with considering the degradation of the light emission power of the LED. (50%/5years)
- 3. There are cases that the deviation of the CTR and the degradation of the light emission power of the LED become big at I_F is less than 1.0mA. Please design the circuit with considering this point.

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	l sheet-1-2

4. Precautions for Soldering Photocouplers

(1) If solder reflow:

It is recommended that only one soldering be done at the temperature and the time within the temperature profile as shown in the figure below.



Since, influence to the device is different according to reflow equipment and its condition, please use the device after confirming no damage in the actual using condition.

(2) Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item (1). Also avoid immersing the resin part in the solder.